



# ISTFA/2018 FAILURES WORTH ANALYZING

## 2018 ORGANIZING COMMITTEE



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LatticeGear



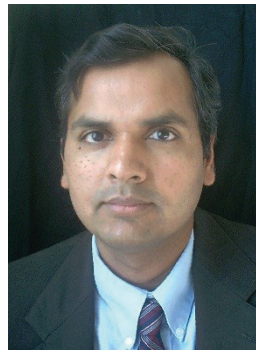
**Dr. Felix Beaudoin**  
Vice General Chair  
  
GLOBALFOUNDRIES



**Dr. David Grosjean**  
Technical Program Chair  
  
Butterfly Networks, Inc.



**Dr. Mayue Xie**  
Tutorial & Short Course  
Chair  
  
Intel



**Dr. Sam Subramanian**  
Immediate Past General Chair  
NXP Semiconductors

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Tutorial & Short Course Vice Chair
- Zhigang Song**  
Audio Visual Co-Chair
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User Groups Vice Chair
- Rose Ring**  
Movie Chair
- Navid Asadi**  
Publicity (Academia) Chair

- Susan Li**  
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Panel Co-Chair
- Patrick Pardy**  
User Groups Chair
- Becki Watt**  
Expo Chair
- Vinod Narang (Asia)**  
International Co-Chair
- Anita Madan**  
User Group Co-Chair

### ISTFA 2018 TECHNICAL PROGRAM COMMITTEE



#### ISTFA 2018 Technical Program Chair

**Dr. David Grosjean**  
Butterfly Networks, Inc.

#### Session Chairs

##### 3D Device Failure Analysis

Christian Schmidt, *NVIDIA*  
Jesse Alton, *TeraView LTD*

##### Board and System Level FA

Jason Wheeler, *Raytheon*  
Becky Holdford, *Texas Instruments*

##### Detecting and Preventing Counterfeit Microelectronics

Michael D. Woo, *Raytheon*  
Michael H. Azarian, *CALCE, University of Maryland*

##### Emerging FA Techniques and Concepts

Dan Bodoh, *NXP Semiconductors*  
Frank Altmann, *Fraunhofer Institute for Mechanics of Materials*

##### FA Processes Case Studies

Erwin Hendarto, *Silicon Labs*  
Chuan Zhang, *GLOBALFOUNDRIES*

##### Fault Isolation

Keith A. Serrels, *NXP Semiconductors*  
Joe Caroselli, *AMD*

##### FIB Circuit Analysis and Edit

Ken Lagarec, *Fibics Incorporated*  
Shida Tan, *Intel*

##### FIB Sample Preparation

Bryan Tracy, *Evans Analytical Group*  
Antonio Tollis, *Analog Devices*

##### Hardware Attacks, Security, and Reverse Engineering

Domenic Forte, *University of Florida*  
Ujjwal Guin, *Auburn University*

##### Low Power Devices and Test Structures Case Studies

Michael Bruce, *Consultant*  
Rose Ring, *LAM Research*

##### Microscopy

Lianfeng Fu, *Lam Research Corporation*  
Edgar Voelkl, *Consultant*

##### Mixed Mode & High Power Devices Case Studies

Stephen T. Fasolino, *Raytheon*  
Jared Eisenhower, *Medtronic*

##### Nanoprobng and Electrical Characterization

Sweta Pendyala, *GLOBALFOUNDRIES*  
John Sanders, *Thermo Fisher Scientific*

##### Packaging & Assembly Level FA

Peng Li, *Intel Corporation*  
Kannu Wadhwa, *ZEISS*

##### Product Yield, Test & Diagnostics

Jayant Dsouza, *Mentor, A Siemens Business*  
Amit M. Jakati, *GLOBALFOUNDRIES*

##### Sample Preparation and Device Deprocessing

Ryan Fredrickson, *On Semiconductor*  
Hueihao Yap, *GLOBALFOUNDRIES*

##### Scanning Probe Analysis

Phil Kaszuba, *GLOBALFOUNDRIES*  
Paiboon Tangyunyong, *Sandia National Laboratories*

##### Space Application FA

Ted Kolasa, *Orbital ATK*  
Richard Blank, *California Institute of Technology*